

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2539	257/777	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 19:33
S2	639	"257" and reflowed near solder	USPAT	OR	ON	2004/09/16 11:31
S3	4106	257/778	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:59
S4	1717	257/779	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 12:48
S5	2016	257/780	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 13:08
S6	1054	257/781	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 13:18
S7	3765	257/723	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 13:57
S8	2624	257/724	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 15:31
S9	1190	257/685	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 15:43
S10	2767	257/686	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 16:02

S11	2720	257/690	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 16:21
S12	15	metal near ball with (copper or "Cu") with (melt\$3 or reflow\$3)	USPAT	OR	ON	2004/09/16 16:12
S13	7	metal near ball with (copper or "Cu") same metal near ball with (reflow\$3)	USPAT	OR	ON	2004/09/16 16:13
S14	2699	257/700	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 17:22
S15	389	solder with high near temperature and solder with low near temperature	USPAT	OR	OFF	2004/09/16 18:49
S16	8	solder near ("HMT" or HJT) and solder near ("LMT" or LJT)	USPAT	OR	OFF	2004/09/16 18:49
S17	1	(solder with high near temperature and solder with low near temperature) and off near set	USPAT	OR	OFF	2004/09/16 17:55
S18	8	solder with ("HMT" or HJT) and solder with ("LMT" or LJT)	USPAT	OR	ON	2004/09/16 18:49
S19	1086	solder with high with temperature and solder with low with temperature	USPAT	OR	ON	2004/09/16 18:50
S20	117	solder near (ball or bump) with high with temperature and solder near (ball or bump) with low with temperature	USPAT	OR	ON	2004/09/16 19:18
S21	1	"3871015".PN.	USPAT	OR	OFF	2004/09/16 19:10
S22	1	"4536786".PN.	USPAT	OR	OFF	2004/09/16 19:12
S23	1	"4604644".PN.	USPAT	OR	OFF	2004/09/16 19:12
S24	1	"5216278".PN.	USPAT	OR	OFF	2004/09/16 19:12
S25	1	"5569960".PN.	USPAT	OR	OFF	2004/09/16 19:12
S26	1	"5569960".PN.	USPAT	OR	OFF	2004/09/16 19:18
S27	1	"3871015".PN.	USPAT	OR	OFF	2004/09/16 19:18
S28	21	"5569960"	USPAT	OR	ON	2004/09/16 19:29
S29	2453	257/738	USPAT	OR	ON	2004/09/16 19:32
S30	209	257/738 and offset	USPAT	OR	ON	2004/09/16 19:56
S31	1	"5068603".PN.	USPAT	OR	OFF	2004/09/16 19:50
S32	1	"5128737".PN.	USPAT	OR	OFF	2004/09/16 19:50
S33	1	"5161124".PN.	USPAT	OR	OFF	2004/09/16 19:51

S34	1	"5223454".PN.	USPAT	OR	OFF	2004/09/16 19:51
S35	1	"5386623".PN.	USPAT	OR	OFF	2004/09/16 19:51
S36	1	"5432999".PN.	USPAT	OR	OFF	2004/09/16 19:51
S37	1	"5471087".PN.	USPAT	OR	OFF	2004/09/16 19:51
S38	1	"5506499".PN.	USPAT	OR	OFF	2004/09/16 19:51
S39	1	"5629838".PN.	USPAT	OR	OFF	2004/09/16 19:51
S40	1	"5637920".PN.	USPAT	OR	OFF	2004/09/16 19:51
S41	1	"5637920".PN.	USPAT	OR	OFF	2004/09/16 19:52
S42	1	"5640340".PN.	USPAT	OR	OFF	2004/09/16 19:52
S43	1	"5686762".PN.	USPAT	OR	OFF	2004/09/16 19:52
S44	1	"5751065".PN.	USPAT	OR	OFF	2004/09/16 19:52
S45	1	"5808330".PN.	USPAT	OR	OFF	2004/09/16 19:52
S46	1	"5815427".PN.	USPAT	OR	OFF	2004/09/16 19:52
S47	1	"5817540".PN.	USPAT	OR	OFF	2004/09/16 19:53
S48	1	"5843799".PN.	USPAT	OR	OFF	2004/09/16 19:54
S49	1	"5844297".PN.	USPAT	OR	OFF	2004/09/16 19:54
S50	1	"5856705".PN.	USPAT	OR	OFF	2004/09/16 19:54
S51	1	"5859801".PN.	USPAT	OR	OFF	2004/09/16 19:54
S52	1	"5883427".PN.	USPAT	OR	OFF	2004/09/16 19:54
S53	1	"5898223".PN.	USPAT	OR	OFF	2004/09/16 19:54
S54	1	"5905305".PN.	USPAT	OR	OFF	2004/09/16 19:55
S55	1	"5915167".PN.	USPAT	OR	OFF	2004/09/16 19:55
S56	1	"5930162".PN.	USPAT	OR	OFF	2004/09/16 19:55
S57	1	"5936305".PN.	USPAT	OR	OFF	2004/09/16 19:55
S58	1	"5943285".PN.	USPAT	OR	OFF	2004/09/16 19:55
S59	167	257/780 and offset	USPAT	OR	ON	2004/09/16 20:08
S60	1788	257/780	USPAT	OR	ON	2004/09/16 20:50
S61	1	"5138433".PN.	USPAT	OR	OFF	2004/09/16 20:26
S62	1	"5172303".PN.	USPAT	OR	OFF	2004/09/16 20:26
S63	1	"4288841".PN.	USPAT	OR	OFF	2004/09/16 20:28
S64	1	"4437718".PN.	USPAT	OR	OFF	2004/09/16 20:28
S65	1	"4617730".PN.	USPAT	OR	OFF	2004/09/16 20:28
S66	1	"4654694".PN.	USPAT	OR	OFF	2004/09/16 20:28
S67	1	"4691225".PN.	USPAT	OR	OFF	2004/09/16 20:28
S68	1	"4940181".PN.	USPAT	OR	OFF	2004/09/16 20:28
S69	1	"4969827".PN.	USPAT	OR	OFF	2004/09/16 20:28
S70	1	"5016138".PN.	USPAT	OR	OFF	2004/09/16 20:29
S71	1	"5138433".PN.	USPAT	OR	OFF	2004/09/16 20:29

S72	1	"5241133".PN.	USPAT	OR	OFF	2004/09/16 20:29
S73	1	"5239198".PN.	USPAT	OR	OFF	2004/09/16 20:29
S74	1	"5172303".PN.	USPAT	OR	OFF	2004/09/16 20:29
S75	1	"5285352".PN.	USPAT	OR	OFF	2004/09/16 20:29
S76	1	"5293072".PN.	USPAT	OR	OFF	2004/09/16 20:31
S77	1	"5303119".PN.	USPAT	OR	OFF	2004/09/16 20:31
S78	1	"5308443".PN.	USPAT	OR	OFF	2004/09/16 20:31
S79	1	"5468999".PN.	USPAT	OR	OFF	2004/09/16 20:31
S80	1	"5523622".PN.	USPAT	OR	OFF	2004/09/16 20:33
S81	1	"5541450".PN.	USPAT	OR	OFF	2004/09/16 20:33
S82	1	"4849857".PN.	USPAT	OR	OFF	2004/09/16 20:48
S83	1	"4855867".PN.	USPAT	OR	OFF	2004/09/16 20:48
S84	1	"5349501".PN.	USPAT	OR	OFF	2004/09/16 20:48
S85	1	"5357400".PN.	USPAT	OR	OFF	2004/09/16 20:48
S86	1	"5365107".PN.	USPAT	OR	OFF	2004/09/16 20:48
S87	1	"5438224".PN.	USPAT	OR	OFF	2004/09/16 20:49
S88	1	"5448106".PN.	USPAT	OR	OFF	2004/09/16 20:49
S89	1	"5450283".PN.	USPAT	OR	OFF	2004/09/16 20:49
S90	1	"5506756".PN.	USPAT	OR	OFF	2004/09/16 20:50
S91	1	"5608262".PN.	USPAT	OR	OFF	2004/09/16 20:50
S92	1	"5672908".PN.	USPAT	OR	OFF	2004/09/16 20:50
S93	90	offset near pad and solder	USPAT	OR	ON	2004/09/16 20:58
S94	1350	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 16:54
S95	2613	257/777	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 16:55
S96	4196	257/778	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 17:12
S97	1743	257/779	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 17:30

S98	2057	257/780	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 17:45
S99	1063	257/781	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 18:03
S10 0	4196	257/778	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 18:01
S10 1	3831	257/723	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 18:12
S10 2	1	"4744008".PN.	USPAT	OR	OFF	2004/10/27 18:06
S10 3	1	"5283468".PN.	USPAT	OR	OFF	2004/10/27 18:07
S10 4	1	"5821624".PN.	USPAT	OR	OFF	2004/10/27 18:07
S10 5	2661	257/724	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 18:30
S10 6	1209	257/685	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 18:47
S10 7	2825	257/686	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 19:06
S10 8	2768	257/690	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 19:23
S10 9	3612	(semiconductor or die or chip or Ic) with wir\$3 and solder near (ball or bump) and (encapsulat\$3 or mold\$3)	USPAT	OR	ON	2004/10/27 22:23

S11 0	487	((semiconductor or die or chip or Ic) with wir\$3 and solder near (ball or bump) and (encapsulat\$3 or mold\$3) ) and (ball or bump) with (big or large)	USPAT	OR	ON	2004/10/27 22:24
S11 1	2749	257/700	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 20:00
S11 2	2211	438/108	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 20:25
S11 3	37	"5844315"	USPAT	OR	OFF	2004/10/27 20:12
S11 4	1	"5019673".PN.	USPAT	OR	OFF	2004/10/27 20:09
S11 5	1	"5218759".PN.	USPAT	OR	OFF	2004/10/27 20:09
S11 6	1	"5220489".PN.	USPAT	OR	OFF	2004/10/27 20:09
S11 7	1	"5241133".PN.	USPAT	OR	OFF	2004/10/27 20:09
S11 8	1	"5278726".PN.	USPAT	OR	OFF	2004/10/27 20:09
S11 9	1	"5285352".PN.	USPAT	OR	OFF	2004/10/27 20:09
S12 0	1	"5334857".PN.	USPAT	OR	OFF	2004/10/27 20:09
S12 1	1	"5608265".PN.	USPAT	OR	OFF	2004/10/27 20:10
S12 2	1	"5616958".PN.	USPAT	OR	OFF	2004/10/27 20:11
S12 3	1	"5677566".PN.	USPAT	OR	OFF	2004/10/27 20:11
S12 4	35	"5608265"	USPAT	OR	OFF	2004/10/27 20:12
S12 5	1045	438/109	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 20:42

S12 6	3850	361/760	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/27 21:34
S12 7	0	stack\$3 near (semiconductor or chip or die) and (lower or bottom) near (semiconductor or chip or die) with memory and (upper or top) near (semiconductor or chip or die) with "microprocessor."	USPAT	OR	OFF	2004/10/27 21:40
S12 8	0	(lower or bottom) near (semiconductor or chip or die) with memory and (upper or top) near (semiconductor or chip or die) with "microprocessor."	USPAT	OR	OFF	2004/10/27 21:36
S12 9	0	stack\$3 near (semiconductor or chip or die) and (semiconductor or chip or die) near memory and (semiconductor or chip or die) near "microprocessor."	USPAT	OR	OFF	2004/10/27 21:37
S13 0	0	stack\$3 near (semiconductor or chip or die) and (semiconductor or chip or die) with memory and (semiconductor or chip or die) with "microprocessor."	USPAT	OR	OFF	2004/10/27 21:39
S13 1	0	257/777 and (semiconductor or chip or die) with memory and (semiconductor or chip or die) with "microprocessor."	USPAT	OR	OFF	2004/10/27 21:37
S13 2	0	(semiconductor or chip or die) with memory and (semiconductor or chip or die) with "microprocessor."	USPAT	OR	OFF	2004/10/27 21:37
S13 3	0	(semiconductor or chip or die) with memor\$3 and (semiconductor or chip or die) with micro near "processor."	USPAT	OR	ON	2004/10/27 21:38
S13 4	0	(semiconductor or chip or die or IC) with memor\$3 and (semiconductor or chip or die or IC) with "microprocessor."	USPAT	OR	ON	2004/10/27 21:39
S13 5	91434	(semiconductor or chip or die or IC) with memor\$3	USPAT	OR	ON	2004/10/27 21:38
S13 6	0	(semiconductor or chip or die or IC) with "microprocessor."	USPAT	OR	ON	2004/10/27 21:39
S13 7	0	(semiconductor or chip or die or IC) with micro near "processor."	USPAT	OR	ON	2004/10/27 21:39
S13 8	0	(semiconductor or chip or die or IC) with "micro-processor."	USPAT	OR	ON	2004/10/27 21:39

S13 9	22456	(semiconductor or chip or die or IC) with microprocessor	USPAT	OR	ON	2004/10/27 21:39
S14 0	188	stack\$3 near (semiconductor or chip or die) and (semiconductor or chip or die) with memory and (semiconductor or chip or die) with microprocessor	USPAT	OR	OFF	2004/10/27 21:40
S14 1	0	stack\$3 near (semiconductor or chip or die) and (lower or bottom) near (semiconductor or chip or die) with memory and (upper or top) near (semiconductor or chip or die) with microprocessor	USPAT	OR	OFF	2004/10/27 21:40
S14 2	5	(lower or bottom) near (semiconductor or chip or die) with memory and (upper or top) near (semiconductor or chip or die) with microprocessor	USPAT	OR	OFF	2004/10/27 22:45
S14 3	0	((semiconductor or die or chip or Ic) with wir\$3 and solder near (ball or bump) and (encapsulat\$3 or mold\$3) ) and (ball or bump) with (big or large)	JPO	OR	ON	2004/10/27 22:24
S14 4	104	(semiconductor or die or chip or Ic) with wir\$3 and solder near (ball or bump) and (encapsulat\$3 or mold\$3)	JPO	OR	ON	2004/10/27 22:24
S14 5	5	((lower or bottom) near (semiconductor or chip or die) with memory and (upper or top) near (semiconductor or chip or die) with microprocessor) and (semiconductor or chip or die) with memory and (semiconductor or chip or die) with microprocessor	USPAT	OR	OFF	2004/10/28 10:25
S14 6	9	"5222014".pn. or "5854534".pn. or "6020633".pn. or "6031729".pn. or "6111756".pn. or "6127726".pn. or "6137167".pn. or "6239496".pn. or "6274937".pn.	USPAT	OR	OFF	2004/10/28 10:28
S14 7	2	"20040262728".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 19:36
S14 8	1	"6388333".pn. and (encapsulat\$3 or mold\$3) with (contact\$3 or attach\$3 or touch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 19:55



S14 9	0	"6770980".pn. and (encapsulat\$3 or mold\$3) with (contact\$3 or attach\$3 or touch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 19:54
S15 0	430	257/777 and (encapsulat\$3 or mold\$3) with (contact\$3 or attach\$3 or touch\$3) and wir\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 20:15
S15 1	518	257/686 and (encapsulat\$3 or mold\$3) with (contact\$3 or attach\$3 or touch\$3) and wir\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 20:15